SAMSUNG ELECTRO-MECHANICS

Ver 201305

Chip Bead For EMI Suppression

CIM03 Series (0603/ EIA 0201)



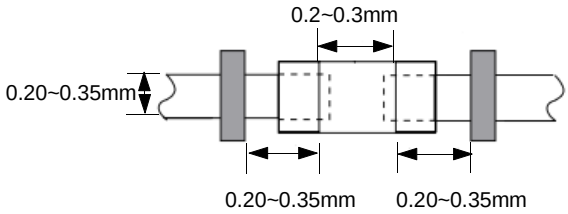
APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

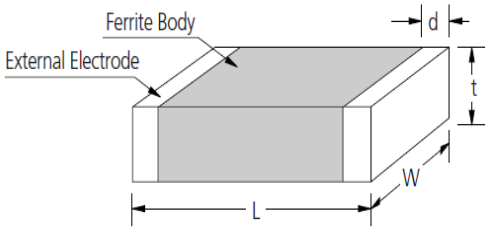
FEATURES

- The smallest beads suitable for surface mounting
- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

RECOMMENDED LAND PATTERN



DIMENSION



Type	Dimension [mm]			
	L	W	t	d
03	0.6±0.03	0.3±0.03	0.3±0.03	0.15±0.05

DESCRIPTION

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIM 03N 300	0.3±0.03	30	0.70	150
CIM 03N 800	0.3±0.03	80	1.20	100
CIM 03U 800	0.3±0.03	80	0.40	200
CIM 03U 121	0.3±0.03	120	0.50	200
CIM 03U 241	0.3±0.03	240	0.75	200
CIM 03U 471	0.3±0.03	470	1.30	100
CIM 03U 601	0.3±0.03	600	1.50	100
CIM 03J 121	0.3±0.03	120	0.50	200
CIM 03J 241	0.3±0.03	240	1.00	100

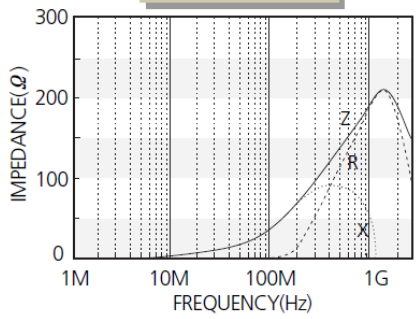
*Operating temperature range –55 to +125℃

※Measurement equipment & Jig

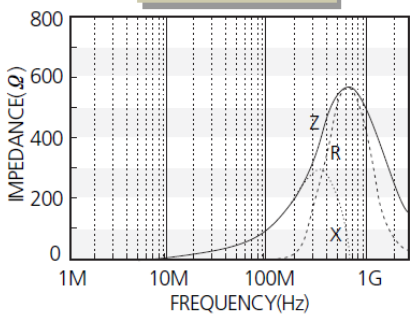
- Impedance Measuring equipment & Jig : Agilent E4991A + 16197A Bottom Electrode SMD Test Fixture or Equivalent
- Resistance Measuring equipment & Jig : Agilent 4338A + 16089A Large Kelvin Clip Leads or Equivalent

CHARACTERISTIC DATA

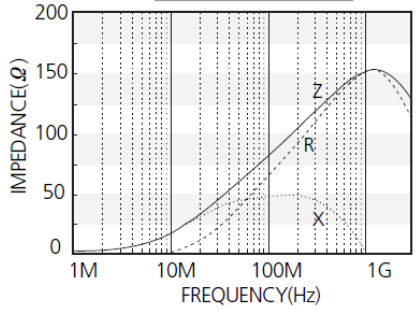
CIM03N300



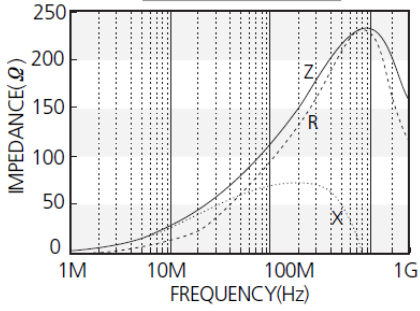
CIM03N800



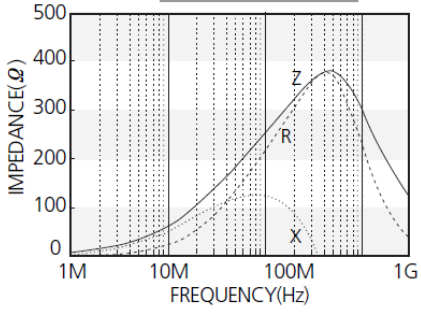
CIM03U800



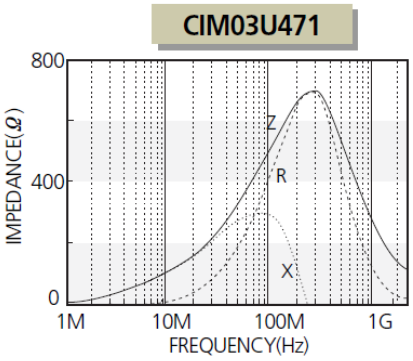
CIM03U121



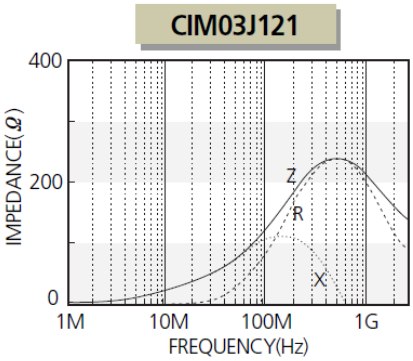
CIM03U241



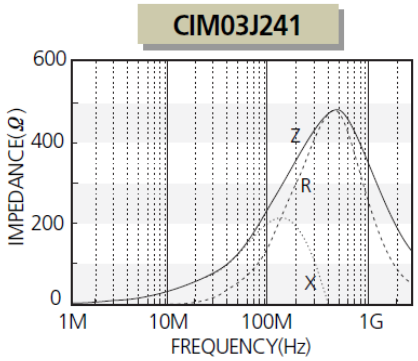
CIM03U471



CIM03J121



CIM03J241



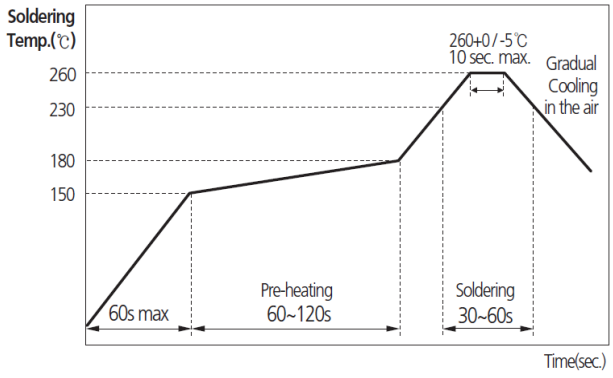
PRODUCT IDENTIFICATION

CI	M	03	U	121	N	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)

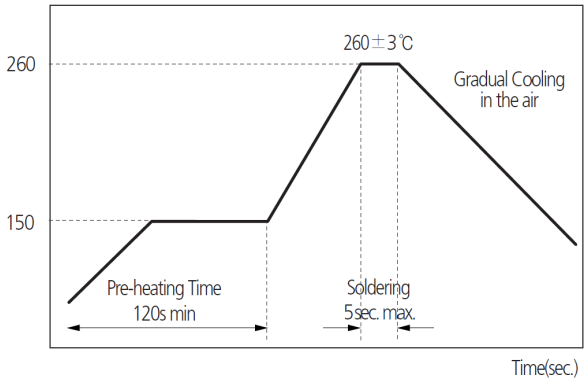
(1) Chip Beads
(2) M: Multi-layer type B:Mono-layer type
(3) Dimension
(4) Material Code
(5) Nominal impedance (100:10Ω, 121:120Ω)
(6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
(7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	10,000

Any data in this sheet are subject to change, modify or discontinue without notice.
The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.